

AMENDMENTS TO THE SPECIFICATION

[0028] **Figure 6** is a top perspective view of a stack of memory circuits on thinned single crystal layers 50 formed according to the techniques described herein. Memory circuits 50 are stacked one on top of another over an area of circuit board 70 and isolated from one another by, for example, a dielectric material (not shown). Vias and interconnects 125 are disposed between the different layers of memory circuits to communicate, for example, between each other, or between circuits on circuit board 70.